

Product Change Notification - KSRA-23ENWX184

Date:

26 Apr 2019

Product Category:

Others; Computing Embedded Controllers

Affected CPNs:

Notification subject:

CCB 3780 Initial Notice: Qualification of MMT as an additional assembly site for selected products of the 65nm GF wafer technology available in 128L TQFP (14x14x1mm) package using CuPdAu bond wire.

Notification text:
PCN Status:

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and).

Description of Change:

Qualification of MMT as an additional assembly site for selected products of the 65nm GF wafer technology available in 128L TQFP (14x14x1mm) package using CuPdAu bond wire.

Pre Change:

Assembled at using palladium coated copper (PdCu) bond wire, 1076WA die attach, and G631H molding compound material.

Post Change:

Assembled at using palladium coated copper (PdCu) bond wire, 1076WA die attach, and G631H molding compound material. Assembled at using palladium coated copper with gold flash (CuPdAu) bond wire, 3280 die attach, and G700HA molding compound material.

Pre and Post Change Summary:

	Pre Change		Post Change	
Assembly Site	ASE Inc. / ASE	ASE Inc. / ASE	Microchip (Branch) / MMT	
Wire material				
Die attach material	1076WA	1076WA	3280	
Molding compound material	G631H	G631H	G700HA	
Lead frame material	C7025	C7025	C7025	

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

June 2019



Note: Please be advised the qualification completion times may be extended because of unforeseen business implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and . Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	April 2019					-->	June 2019				
	14	15	16	17	18		23	24	25	26	27
Initial PCN Issue Date				X							
Report Availability										X	
Final PCN Issue Date										X	

Method to Identify Change:

code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:

April 26, 2019: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_KSRA-23ENWX184_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

MEC1322I-NU-C0

MEC1322-NU

MEC1322-NU-C0

MEC1324-NU

MEC1404-NU

MEC1404-NU-D0

MEC1406-NU

MEC1406-NU-D0

MEC1408-NU

MEC1414-I/NU

MEC1414-NU

MEC1416-I/NU

MEC1416-NU

MEC1416-NU-D0

MEC1418-I/NU

MEC1418-NU

MEC1418-NU-D0

MEC1428-I/NU-C1

MEC1428-NU-C1